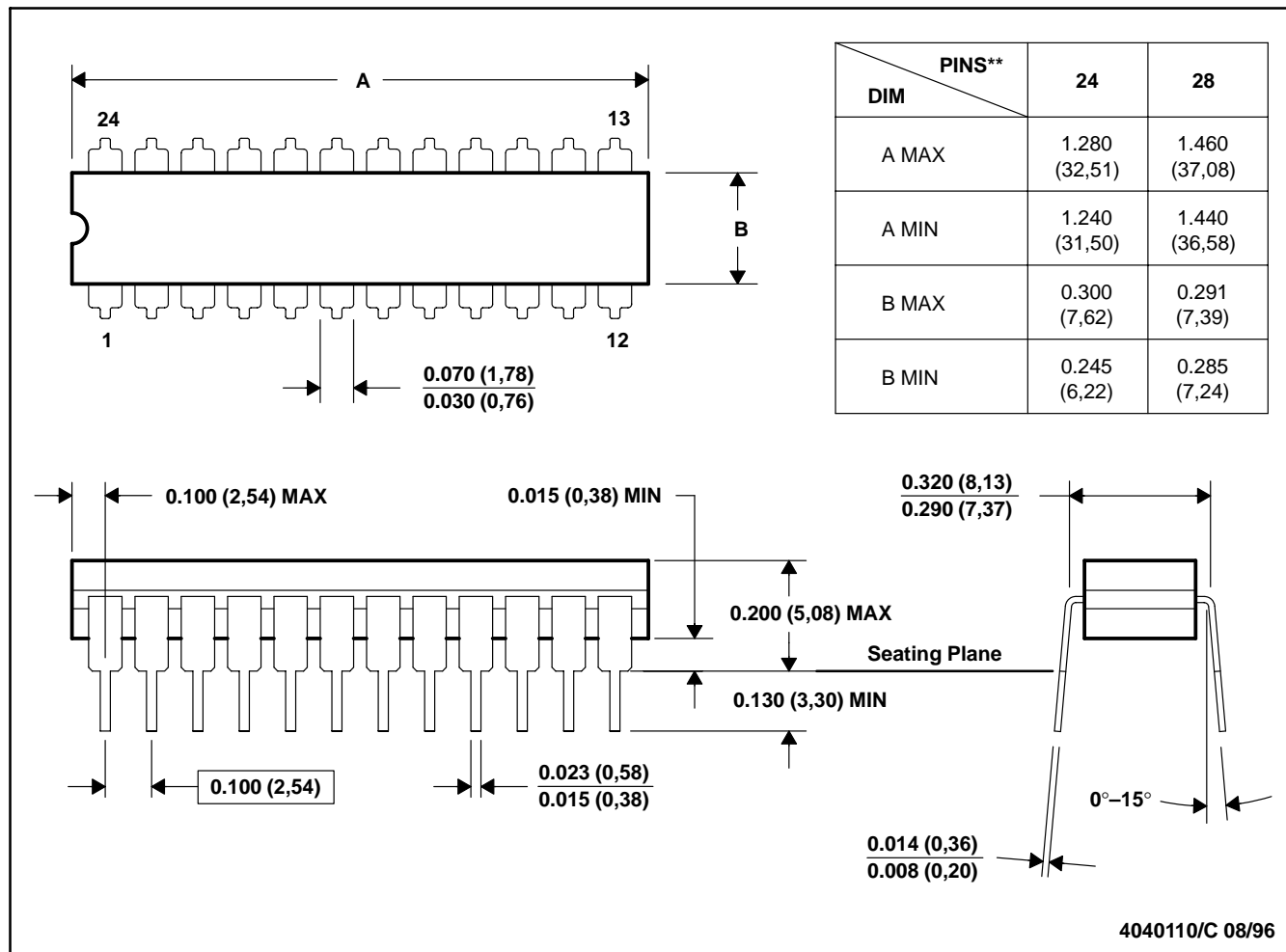


JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP-T24, GDIP-T28 and JEDEC MO-058 AA, MO-058 AB.

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